

PRODUCT CHANGE NOTIFICATION



Linear Technology Corporation
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February 9, 2017

PCN#020917

Dear Sir/Madam:

Subject: Notification of Change to LTC3886 Die and Datasheet

Please be advised that Linear Technology Corporation has made enhancements to the LTC3886 product die to improve performance in the following areas:

- 1) Fix errata
- 2) Reduce power up times
- 3) Reduce the ADC update period
- 4) Improve on-chip EEPROM robustness

The documented errata in the LTC3886 are eliminated. Refer to the following link for the current errata documents <http://cds.linear.com/docs/en/spec-notice/er3886f.pdf>.

T_{INIT} , the time required from application of VIN until the part is ready to start sequencing output rails, is reduced from a typical value of 70ms to 35ms. This may allow applications to power up faster after application of VIN. This change is transparent in all applications that require sequencing of multiple power rails using multiple LTC Power System Management (PSM) parts connected in the recommended manner.

The ADC update period, $T_{CONVERT}$, is reduced from 100ms to 90ms, providing more timely telemetry of all monitored parameters.

The above changes are shown on the attached pages of the marked up datasheet.

Error Correcting Code (ECC) is added to the internal non-volatile memory to enhance its reliability. This change is transparent to the user and requires no modifications to programming files or system firmware. As a consequence of adding ECC, the area in the EEPROM available for fault log is reduced to 4 events. The read length of 147 bytes remains the same but the fifth and sixth events are a repeat of the fourth event if the part is reset. However, when reading the fault log from RAM, all 6 events of cyclical data are available.

The new silicon can be identified by the MFR_SPECIAL_ID, PMBus command code 0xE7, with a value of 0x460* where * is a value of 8-F.

No changes were made to the analog sections of the LTC3886, and no PWM characteristics changed. The die changes were qualified by performing characterization over the full operating junction temperature range and through rigorous engineering evaluation across a broad range of application conditions. The revised product will have successfully completed 1000 hours burn-in before production release.

Linear Technology will accept requests for revised samples within 30 days of the date of this notification. If we don't hear back from your company within this 30 day period, we will consider this change notice accepted by April 09, 2017. Production shipments of product incorporating the improved die will begin no sooner than April 09, 2017.

Should you have any further questions, please feel free to contact your local Linear Technology sales person or you may contact me at 408-432-1900 ext. 2077, or by E-mail JASON.HU@LINEAR.COM.

Sincerely,

Jason Hu

Quality Assurance Engineer

ELECTRICAL CHARACTERISTICS The ● denotes the specifications which apply over the specified operating junction temperature range, otherwise specifications are at $T_J = 25^\circ\text{C}$ (Note 2). $V_{IN} = 16\text{V}$, $\text{EXTV}_{CC} = 0\text{V}$, $V_{RUN0} = 3.3\text{V}$, $V_{RUN1} = 3.3\text{V}$, $f_{\text{SYNC}} = 350\text{kHz}$ (externally driven), and all programmable parameters at factory default unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Input Voltage						
V_{IN}	Input Voltage Range	(Note 12)	●	4.5	60	V
I_Q	Input Voltage Supply Current Normal Operation	(Note 14) $V_{RUN} = 3.3\text{V}$, No Caps on TG and BG $V_{RUN} = 0\text{V}$		26 22		mA mA
V_{UVLO}	Undervoltage Lockout Threshold When $V_{IN} > 4.2\text{V}$	V_{INTVCC} Falling V_{INTVCC} Rising		3.7 3.95		V V
T_{INIT}	Initialization Time	Delay from RESTORE_USER_ALL, MFR_REST, or $V_{INTVCC} > V_{UVLO}$ Until TON_DELAY Can Begin		-70	35	ms
Control Loop						
V_{OUTR0}	Range 0 Maximum V_{OUT} Range 0 Set Point Accuracy Range 0 Resolution Range 0 LSB Step Size, FSR = 16.38	$2.0\text{V} \leq V_{OUT} \leq 13.8\text{V}$ (Note 10)	●	-0.5	14.0 12 4	0.5 Bits mV
V_{OUTR1}	Range 1 Maximum V_{OUT} Range 1 Set Point Accuracy Range 1 Resolution Range 1 LSB Step Size, FSR = 8.19V	$1.0\text{V} \leq V_{OUT} \leq 6.6\text{V}$	●	-0.5	7.0 12 2	0.5 Bits mV
V_{LINREG}	Line Regulation	$16\text{V} < V_{IN} < 60\text{V}$	●		± 0.02	%/V
$V_{LOADREG}$	Load Regulation	$\Delta V_{TH} = 1.35\text{V} - 0.7\text{V}$ $\Delta V_{TH} = 1.35\text{V} - 2.0\text{V}$	● ●	0.01 -0.01	0.1 -0.1	% %
$g_{m0,1}$	Resolution Error Amplifier $g_{m(\text{MAX})}$ Error Amplifier $g_{m(\text{MIN})}$ Error Amplifier g_m LSB Step Size	$I_{TH} = 1.35\text{V}$ $I_{TH} = 1.35\text{V}$ $I_{TH} = 1.35\text{V}$			3 5.76 1.00 0.68	bits mmho mmho mmho
$R_{ITHR0,1}$	Resolution Compensation Resistor $R_{THR(\text{MAX})}$ Compensation Resistor $R_{THR(\text{MIN})}$				5 62 0	bits k Ω k Ω
I_{SENSE}	Input Current	$V_{\text{SENSE}} = 14\text{V}$	●		± 1 ± 2	μA
$V_{I(\text{LIMIT})}$	Resolution $V_{I(\text{LIM}(\text{MAX}))}$ $V_{I(\text{LIM}(\text{MIN}))}$	Hi Range Lo Range Hi Range Lo Range	● ●		3 68 44 75 50 82 56 37.5 25	bits mV mV mV mV
Gate Driver						
TG t_r t_f	TG Transition Time: Rise Time Fall Time	(Note 4) $C_{\text{LOAD}} = 3300\text{pF}$ $C_{\text{LOAD}} = 3300\text{pF}$			30 30	ns ns
BG t_r t_f	BG Transition Time: Rise Time Fall Time	(Note 4) $C_{\text{LOAD}} = 3300\text{pF}$ $C_{\text{LOAD}} = 3300\text{pF}$			20 20	ns ns
TG/BG t_{1D}	Top Gate Off to Bottom Gate On Delay Time	(Note 4) $C_{\text{LOAD}} = 3300\text{pF}$			10	ns
BG/TG t_{2D}	Bottom Gate Off to Top Gate On Delay Time	(Note 4) $C_{\text{LOAD}} = 3300\text{pF}$			30	ns
$t_{\text{ON}(\text{MIN})}$	Minimum On-Time				90	ns

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SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
OV/UV Output Voltage Supervisor						
N	Resolution			9		Bits
V_{RANGE0}	Range 0 Maximum Threshold			14		V
V_{RANGE1}	Range 1 Maximum Threshold			7		V
V_{OUSTP0}	Range 0 Step Size, $\text{FSR} = 16.352\text{V}$	(Note 10)		32		mV
V_{OUSTP1}	Range 1 Step Size, $\text{FSR} = 8.176\text{V}$			16		mV
V_{THACC0}	Range 0 Threshold Accuracy	$2\text{V} < V_{\text{OUT}} < 14\text{V}$	●		± 2.5	%
V_{THACC1}	Range 1 Threshold Accuracy	$1\text{V} < V_{\text{OUT}} < 7\text{V}$	●		± 2.5	%
t_{PROPOV1}	OV Comparator to FAULT Low Time	$V_{\text{OD}} = 10\%$ of Threshold			35	μs
t_{PROPUV1}	UV Comparator to FAULT Low Time	$V_{\text{OD}} = 10\%$ of Threshold			100	μs
V_{IN} Voltage Supervisor						
N	Resolution			9		Bits
$V_{\text{IN(RANGE)}}$	Full-Scale Voltage	(Note 11)	4.5		61.32	V
$V_{\text{IN(STP)}}$	Step Size			120		mV
$V_{\text{IN(THACC)}}$	Threshold Accuracy $12\text{V} < V_{\text{IN}} < 60\text{V}$		●		± 3	%
$V_{\text{IN(THACL)}}$	Threshold Accuracy $4.5\text{V} < V_{\text{IN}} < 15\text{V}$		●		± 6	%
$t_{\text{PROP(VIN)}}$	Comparator Response Time ($V_{\text{IN_ON}}$ and $V_{\text{IN_OFF}}$)	$V_{\text{OD}} = 10\%$ of Threshold			100	μs
Output Voltage Readback						
N	Resolution			16		Bits
	LSB Step Size			250		μV
$V_{\text{F/S}}$	Full-Scale Sense Voltage	(Note 10) $V_{\text{RUN}} = 0\text{V}$ (Note 8)		16.384		V
$V_{\text{OUT_TUE}}$	Total Unadjusted Error	$T_J = 25^\circ\text{C}$, $V_{\text{OUT}} > 1.0\text{V}$ (Note 8)	●	0.2	± 0.5	%
V_{OS}	Zero-Code Offset Voltage		●		± 500	μV
t_{CONVERT}	Conversion Time	(Note 6)		100	90	ms
V_{IN} Voltage Readback						
N	Resolution	(Note 5)		10		Bits
$V_{\text{F/S}}$	Full-Scale Input Voltage	(Note 11)		66.56		V
$V_{\text{IN_TUE}}$	Total Unadjusted Error	$T_J = 25^\circ\text{C}$, $V_{\text{IN}} > 4.5\text{V}$	●		0.4 2	%
t_{CONVERT}	Conversion Time	(Note 6)		100	90	ms
Output Current Readback						
N	Resolution	(Note 5)		10		Bits
	LSB Step Size	$0\text{V} \leq V_{\text{ISENSE}^+} - V_{\text{ISENSE}^-} < 16\text{mV}$		15.26		μV
		$16\text{mV} \leq V_{\text{ISENSE}^+} - V_{\text{ISENSE}^-} < 32\text{mV}$		30.52		μV
		$32\text{mV} \leq V_{\text{ISENSE}^+} - V_{\text{ISENSE}^-} < 64\text{mV}$		61		μV
		$64\text{mV} \leq V_{\text{ISENSE}^+} - V_{\text{ISENSE}^-} < 100\text{mV}$		122		μV
$I_{\text{F/S}}$	Full-Scale Output Current	(Note 7) $R_{\text{ISENSE}} = 1\text{m}\Omega$		± 100		A
$I_{\text{OUT_TUE}}$	Total Unadjusted Error	(Note 8) $10\text{mV} \leq V_{\text{ISENSE}} \leq 100\text{mV}$	●		± 1.5	%
V_{OS}	Zero-Code Offset Voltage				± 32	μV
t_{CONVERT}	Conversion Time	(Note 6)		100	90	ms

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SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS	
Input Current Readback							
N	Resolution	(Note 5)		10		Bits	
	LSB Step Size, Full-Scale Range = 16mV	8x Gain, $0\text{V} \leq I_{IN}^+ - I_{IN}^- \leq 5\text{mV}$		15.26		μV	
	LSB Step Size, Full-Scale Range = 32mV	4x Gain, $0\text{V} \leq I_{IN}^+ - I_{IN}^- \leq 20\text{mV}$		30.52		μV	
	LSB Step Size, Full-Scale Range = 64mV	2x Gain, $0\text{V} \leq I_{IN}^+ - I_{IN}^- \leq 50\text{mV}$		61		μV	
I_{IN_TUE}	Total Unadjusted Error (Note 8)	8x Gain, $2.5\text{mV} \leq I_{IN}^+ - I_{IN}^- \leq 5\text{mV}$ 4x Gain, $4\text{mV} \leq I_{IN}^+ - I_{IN}^- \leq 20\text{mV}$ 2x Gain, $6\text{mV} \leq I_{IN}^+ - I_{IN}^- \leq 50\text{mV}$	● ● ●		± 1.6 ± 1.3 ± 1.2	% % %	
V_{OS}	Zero-Code Offset Voltage				± 50	μV	
t_{CONVERT}	Conversion Time	(Note 6)		100	90	ms	
Supply Current Readback							
N	Resolution	(Note 5)		10		Bits	
	LSB Step Size, Full-Scale Range = 256mV			244		μV	
$I_{\text{CHIP_TUE}}$	Total Unadjusted Error	$20\text{mV} \leq I_{IN}^+ - V_{IN} \leq 200\text{mV}$	●		± 2.5	%	
t_{CONVERT}	Conversion Time	(Note 6)		100	90	ms	
Temperature Readback (T_0, T_1)							
$T_{\text{RES_T}}$	Resolution			0.25		$^\circ\text{C}$	
T_0_TUE	External TSNS TUE (Note 8) MFR_PWM_MODE_LTC3886[5] = 0 MFR_PWM_MODE_LTC3886[5] = 1	$\Delta V_{\text{TSNS}} = 72\text{mV}$ (Note 17)	●		± 3	$^\circ\text{C}$	
		$V_{\text{TSNS}} \leq 1.85\text{mV}$ (Note 17)	●		± 7	$^\circ\text{C}$	
T_1_TUE	Internal TSNS TUE	$V_{\text{RUN}} = 0.0\text{V}$ (Note 8)			± 1	$^\circ\text{C}$	
$t_{\text{CONVERT_T}}$	Update Rate	(Note 6)		100	90	ms	
INTV_{CC} Regulator							
$V_{\text{INTVCC_VIN}}$	Internal V_{CC} Voltage No Load	$6\text{V} < V_{IN} < 60\text{V}$	●	4.8	5	5.2	V
$V_{\text{LDO_VIN}}$	INTV _{CC} Load Regulation	$I_{\text{CC}} = 0\text{mA}$ to 50mA		0.5	± 2	%	
$V_{\text{INTVCC_EXT}}$	Internal V_{CC} Voltage No Load	$5.5\text{V} < \text{EXTV}_{\text{CC}} < 14\text{V}$	●	4.8	5	5.2	V
$V_{\text{LDO_EXT}}$	INTV _{CC} Load Regulation	$I_{\text{CC}} = 0\text{mA}$ to 50mA , $\text{EXTV}_{\text{CC}} = 12\text{V}$		0.5	± 2	%	
$V_{\text{EXT_THRES}}$	EXTV _{CC} Switchover Voltage	EXTV _{CC} Ramping Positive	●	4.5	4.7	4.95	V
$V_{\text{EXT_HYS}}$	EXTV _{CC} Hysteresis Voltage			80		mV	
V_{DD33} Regulator							
V_{DD33}	Internal V_{DD33} Voltage	$4.5\text{V} < V_{\text{INTVCC}}$		3.2	3.3	3.4	V
I_{LIM}	V_{DD33} Current Limit	$V_{\text{DD33}} = \text{GND}$, $V_{IN} = \text{INTV}_{\text{CC}} = 4.5\text{V}$		100		mA	
$V_{\text{DD33_OV}}$	V_{DD33} Overvoltage Threshold			3.5		V	
$V_{\text{DD33_UV}}$	V_{DD33} Undervoltage Threshold			3.1		V	
V_{DD25} Regulator							
V_{DD25}	Internal V_{DD25} Voltage			2.5		V	
I_{LIM}	V_{DD25} Current Limit	$V_{\text{DD25}} = \text{GND}$, $V_{IN} = \text{INTV}_{\text{CC}} = 4.5\text{V}$		80		mA	
Oscillator and Phase-Locked Loop							
f_{OSC}	Oscillator Frequency Accuracy	$100\text{kHz} < f_{\text{SYNC}} < 750\text{kHz}$ Measured Falling Edge-to-Falling Edge of SYNC with SWITCH_FREQUENCY = 100.0 and 750.0	●		± 10	%	
$V_{\text{TH(SYNC)}}$	SYNC Input Threshold	V_{CLKIN} Falling		1		V	
		V_{CLKIN} Rising		1.5		V	
$V_{\text{OL(SYNC)}}$	SYNC Low Output Voltage	$I_{\text{LOAD}} = 3\text{mA}$	●	0.2	0.4	V	
$I_{\text{LEAK(SYNC)}}$	SYNC Leakage Current in Slave Mode	$0\text{V} \leq V_{\text{PIN}} \leq 3.6\text{V}$			± 5	μA	

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LTC3886

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SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
$\theta_{\text{SYNC-}\theta 0}$	SYNC to Channel 0 Phase Relationship Based on the Falling Edge of Sync and Rising Edge of TGO	MFR_PWM_CONFIG_LTC3886[2:0] = 0,2,3		0		Deg
		MFR_PWM_CONFIG_LTC3886[2:0] = 5		60		Deg
		MFR_PWM_CONFIG_LTC3886[2:0] = 1		90		Deg
		MFR_PWM_CONFIG_LTC3886[2:0] = 4,6		120		Deg
$\theta_{\text{SYNC-}\theta 1}$	SYNC to Channel 1 Phase Relationship Based on the Falling Edge of Sync and Rising Edge of TG1	MFR_PWM_CONFIG_LTC3886[2:0] = 3		120		Deg
		MFR_PWM_CONFIG_LTC3886[2:0] = 0		180		Deg
		MFR_PWM_CONFIG_LTC3886[2:0] = 2,4,5		240		Deg
		MFR_PWM_CONFIG_LTC3886[2:0] = 1		270		Deg
		MFR_PWM_CONFIG_LTC3886[2:0] = 6		300		Deg
EEPROM Characteristics						
Endurance	(Note 13)	$0^\circ\text{C} < T_J < 85^\circ\text{C}$ During EEPROM Write Operations	●	10,000		Cycles
Retention	(Note 13)	$T_J < 125^\circ\text{C}$	●	10		Years
Mass_Write	Mass Write Operation Time	STORE_USER_ALL, $0^\circ\text{C} < T_J \leq 85^\circ\text{C}$ During EEPROM Write Operations	●		440 4100	ms
Digital Inputs SCL, SDA, RUN$_n$, FAULT$_n$						
V_{IH}	Input High Threshold Voltage	SCL, SDA, RUN, FAULT	●		2.0	V
V_{IL}	Input Low Threshold Voltage	SCL, SDA, RUN, FAULT	●	1.4		V
V_{HYST}	Input Hysteresis	SCL, SDA		0.08		V
C_{PIN}	Input Capacitance				10	pF
Digital Input WP						
I_{PUWP}	Input Pull-Up Current	WP			10	μA
Open-Drain Outputs SCL, SDA, FAULT$_n$, ALERT, RUN$_n$, SHARE_CLK, PGOOD$_n$						
V_{OL}	Output Low Voltage	$I_{SINK} = 3\text{mA}$	●		0.4	V
Digital Inputs SHARE_CLK, WP						
V_{IH}	Input High Threshold Voltage		●	1.5	1.8	V
V_{IL}	Input Low Threshold Voltage		●	0.6	1.0	V
Leakage Current SDA, SCL, ALERT, RUN						
I_{OL}	Input Leakage Current	$0\text{V} \leq V_{PIN} \leq 5.5\text{V}$	●		± 5	μA
Leakage Current FAULT$_n$, PGOOD$_n$						
I_{GL}	Input Leakage Current	$0\text{V} \leq V_{PIN} \leq 3.6\text{V}$	●		± 2	μA
Digital Filtering of FAULT$_n$						
t_{FAULT}	Input Digital Filtering FAULT $_n$				3	μs
Digital Filtering of PGOOD$_n$						
t_{PGOOD}	Output Digital Filtering PGOOD $_n$				60	μs
Digital Filtering of RUN$_n$						
t_{RUN}	Input Digital Filtering RUN $_n$				10	μs
PMBus Interface Timing Characteristics						
f_{SCL}	Serial Bus Operating Frequency		●	10	400	kHz
t_{BUF}	Bus Free Time Between Stop and Start		●	1.3		μs
$t_{\text{HD(STA)}}$	Hold Time After Start Condition. After This Period, the First Clock Is Generated		●	0.6		μs
$t_{\text{SU(STA)}}$	Repeated Start Condition Setup Time		●	0.6	10000	μs
$t_{\text{SU(STO)}}$	Stop Condition Setup Time		●	0.6		μs
$t_{\text{HD(DAT)}}$	Data Hold Time Receiving Data Transmitting Data		●	0		μs
			●	0.3	0.9	μs

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